

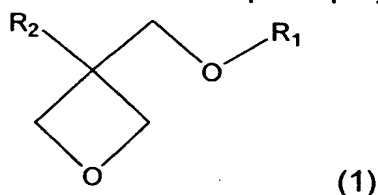
CLAIMS

1. A radiation curable resin composition comprising:

a polyfunctional epoxy polymer (Component A) having a polybutadiene skeleton or a hydrogenated polybutadiene skeleton and two or more glycidyloxy groups in the molecule;

an oxetane compound (Component B) represented by Formula (1) below and/or a monofunctional epoxy compound (Component C) having 8 to 30 carbons; and

a cationic photopolymerization initiator (Component X)



wherein R₁ denotes an optionally branched alkyl group having 6 to 30 carbons, or a phenyl group substituted with an alkyl group having 4 to 30 carbons, and R₂ denotes a hydrogen atom or an optionally branched alkyl group having 1 to 6 carbons.

2. The radiation curable resin composition according to Claim 1, wherein a polyfunctional epoxy compound other than Component A and/or a polyfunctional oxetane compound are not contained at 10 parts or greater relative to 100 parts of the total resin components.

3. The radiation curable resin composition according to Claim 1, wherein the composition comprises a polymer having a glass transition temperature of -30°C or lower (Component D).

4. The radiation curable resin composition according to Claim 3, wherein the polymer (Component D) is a polybutadiene or polyisoprene to which 1 to 20

molecules of maleic anhydride are added per polymer molecule, or one obtained by ring-opening these acid anhydrides with an alcohol

5. The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an antioxidant.
6. The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an inorganic ion-exchanger.
7. The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an antioxidant and an inorganic ion-exchanger.
8. A cured material formed by curing the radiation curable resin composition according to any one of Claims 1 to 4 by irradiation with actinic radiation.
9. A cured material formed by curing the radiation curable resin composition according to Claim 5 by irradiation with actinic radiation.
10. A cured material formed by curing the radiation curable resin composition according to Claim 6 by irradiation with actinic radiation.
11. A cured material formed by curing the radiation curable resin composition according to Claim 7 by irradiation with actinic radiation.
12. The cured material according to Claim 8, wherein the cured material has a storage modulus (G') of 1.2×10^5 Pa or less and a $\tan \delta$ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.
13. The cured material according to Claim 9, wherein the cured material has a storage modulus (G') of 1.2×10^5 Pa or less and a $\tan \delta$ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.
14. The cured material according to Claim 10, wherein the cured material has a storage modulus (G') of 1.2×10^5 Pa or less and a $\tan \delta$ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.
15. The cured material according to Claim 11, wherein the cured material

has a storage modulus (G') of 1.2×10^5 Pa or less and a $\tan \delta$ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.